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[Samsung Electro-Mechanics America, Inc.](#)
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Chip Bead For EMI Suppression

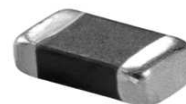
CIB/CIM31 Series (3216/ EIA 1206)

APPLICATION

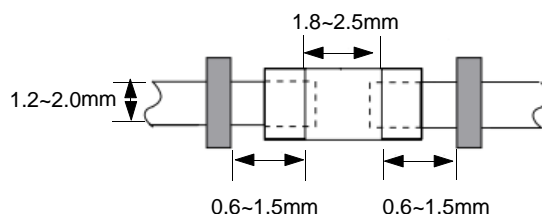
High frequency EMI prevention application to computers, printers, VCRs, TVs and mobile phones.

FEATURES

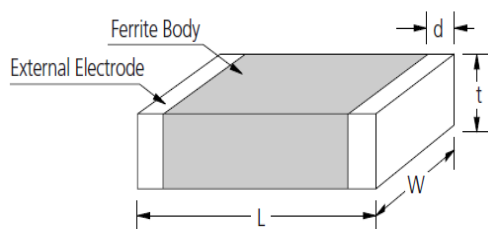
- Perfect shape for automatic mounting, with no directionality.
- Excellent solderability and high heat resistance for either flow or reflow soldering
- Monolithic inorganic material construction for high reliability
- Closed magnetic circuit configuration avoids crosstalk and is suitable for high density PCBs.



RECOMMENDED LAND PATTERN



DIMENSION



Type	Dimension [mm]			
	L	W	t	d
31	3.2±0.2	1.6±0.2	1.1±0.2	0.5+0.2 -0.3

DESCRIPTION

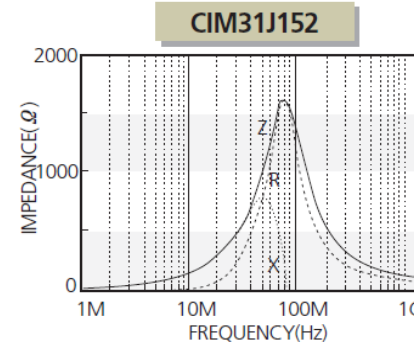
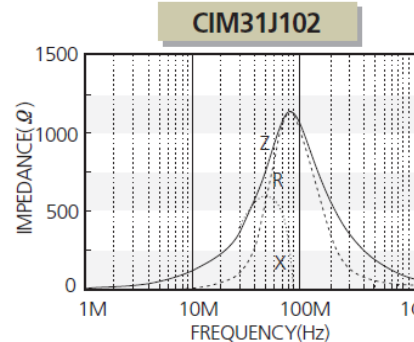
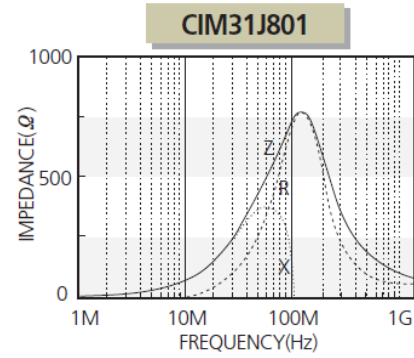
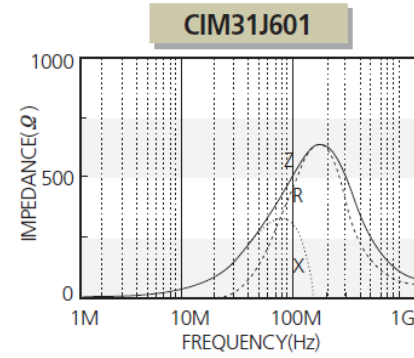
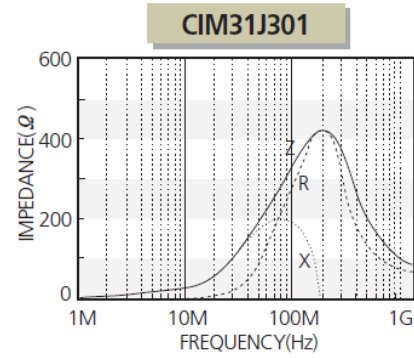
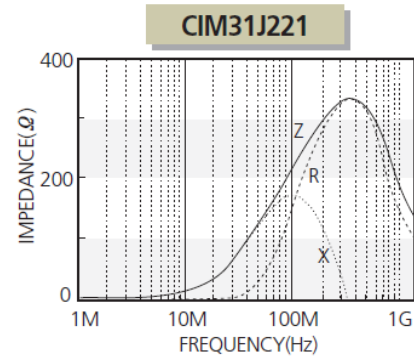
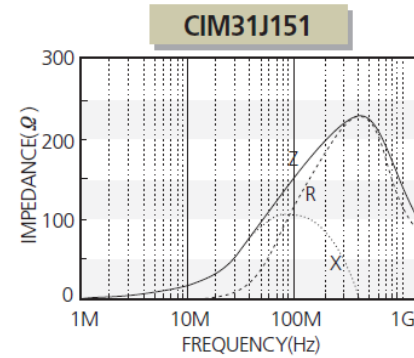
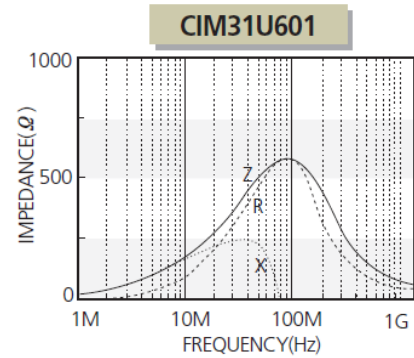
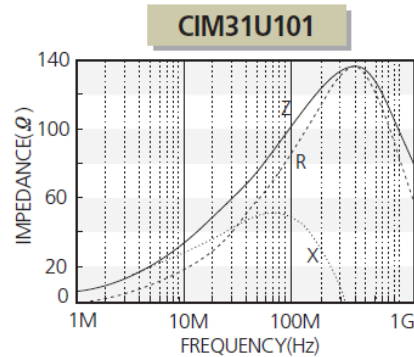
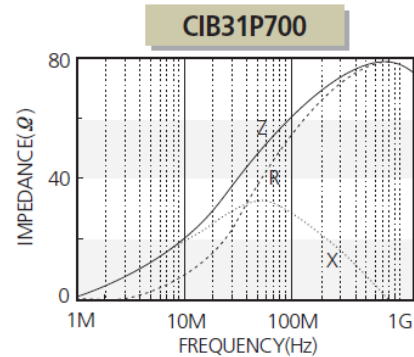
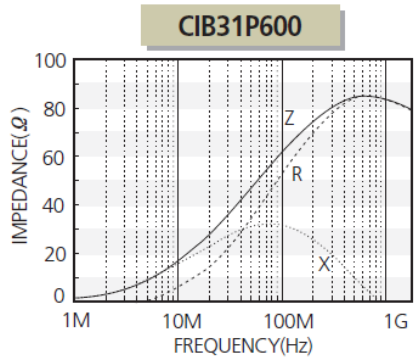
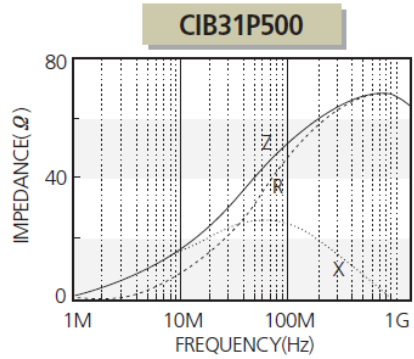
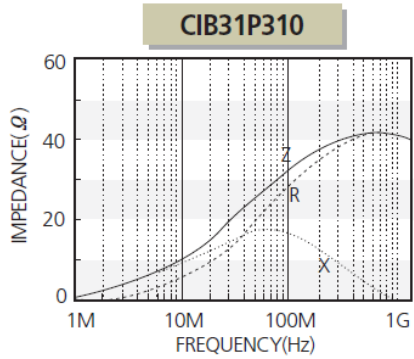
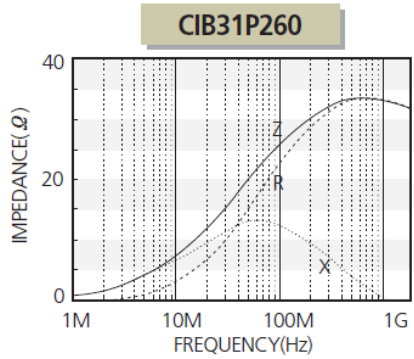
Part no.	Thickness (mm)	Impedance (Ω)±25%@100MHz	DC Resistance (Ω) Max.	Rated Current (mA) Max.
CIB31P260	1.1±0.2	26	0.05	2000
CIB31P310	1.1±0.2	31	0.05	2000
CIB31P500	1.1±0.2	50	0.05	2000
CIB31P600	1.1±0.2	60	0.05	1500
CIB31P700	1.1±0.2	70	0.10	1500
CIM31U101	1.1±0.2	100	0.15	500
CIM31U601	1.1±0.2	600	0.30	400
CIM31J151	1.1±0.2	150	0.20	600
CIM31J221	1.1±0.2	220	0.20	600
CIM31J301	1.1±0.2	300	0.25	600
CIM31J601	1.1±0.2	600	0.30	600
CIM31J801	1.1±0.2	800	0.40	500
CIM31J102	1.1±0.2	1000	0.45	500
CIM31J152	1.1±0.2	1500(at 70MHz)	0.55	300



ELECTRO-MECHANICS

Ver 201305

CHARACTERISTIC DATA





ELECTRO-MECHANICS

Ver 201305

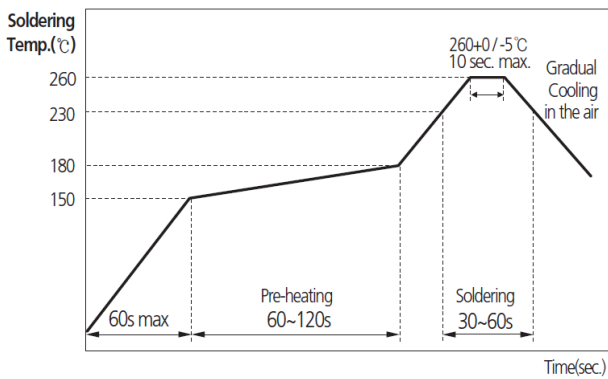
PRODUCT IDENTIFICATION

CI M 31 J 221 N E
(1) (2) (3) (4) (5) (6) (7)

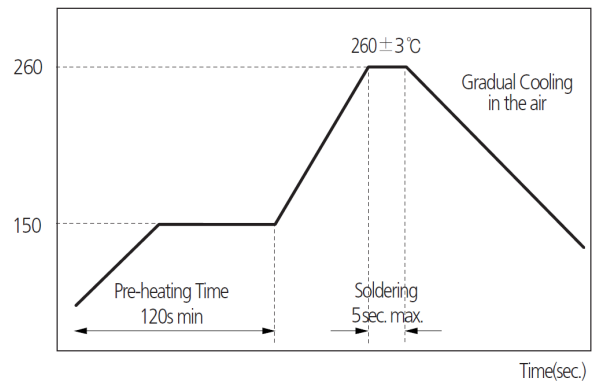
- (1) Chip Beads
- (2) M: Multi-layer type B:Mono-layer type
- (3) Dimension
- (4) Material Code
- (5) Nominal impedance (700:70Ω, 221:220Ω)
- (6) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
- (7) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

Packaging Style	Quantity(pcs/reel)
Card Board Taping	3,000



Any data in this sheet are subject to change, modify or discontinue without notice.

The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers.